

**REMARKS**

Claims 1-5 and 11-25 are pending in this application. By this Amendment, the specification and claims 1-5 are amended and claims 11-25 are added. The specification has been amended for clarification and contains no new matter. Support for new claims 11-25 can be found in the specification including the original claims and the figures, for example, see Figure 2. Reconsideration in view of the above amendments and following remarks is respectfully requested.

I. Specification

The Office Action objects to the specification for various informalities. Applicant respectfully submits that the above amendments obviate the grounds for the objection. Withdrawal of the objection is respectfully requested.

II. Drawings

The Office Action objects to the drawings. However, Applicant respectfully submits that reference sign 52 is illustrated on Figure 3A (as filed) and reference number 101 is illustrated on Figure 3B (as filed). If the drawings received by you do not include these reference numbers, please let us know. Withdrawal of the objection is respectfully requested.

III. 35 U.S.C. §102(e)

The Office Action rejects claims 1-5 under 35 U.S.C. §102(e) over Farrenkopf et al. (U.S. Patent No. 5,899,714). Since Farrenkopf et al. fail to disclose or suggest all the features of the claims, the rejection is respectfully traversed.

Applicant respectfully submits that Farrenkopf et al., as illustrated in Figure 2e, appear to disclose a P-device region 40C and underlying P upper buried region 30C situated in an N-type tub which separates a composite P-type region 40C/36C from a P-substrate region 20. However, Farrenkopf et al. fail to disclose or suggest, as recited in claim 1, at least the feature of a heavily doped region of buried layer having a second conductivity type formed between a first contact region in a first well and an interface between the first well and a semiconductor substrate.

Rather, Farrenkopf et al. fail to disclose or suggest any interface between a first well and a semiconductor substrate, but rather disclose an interface between a P-device region 40C and an epitaxial layer 22 or an interface between the epitaxial layer 22 and a P-substrate region 20.

For at least the reasons set forth above, Applicant respectfully submits that claim 1 is allowable. Claims 2-5 depend from claim 1, and are allowable for at least the same reasons, as well as their added features and the combinations thereof. Withdrawal of the rejection is respectfully requested.

IV. New Claims 11-25

By this Amendment, claims 11-25 are added to the application. New claims 11-25 broadly recite the features of the preferred embodiment(s). It is respectfully submitted that the new claims are allowable over the references of record for at least the reasons discussed above in connection with claims 1-5.

V. Conclusion

In view of the foregoing amendments and remarks, it is respectfully submitted that the application is in condition for allowance. If the Examiner believes that any additional changes would place the application in better condition for allowance, the Examiner is invited to contact the undersigned attorney, Laura L. Lee, at the telephone number listed below. Favorable consideration and prompt allowance are earnestly solicited.

Serial No. 09/955,288

Docket No. LGS/S-0030A

To the extent necessary, a petition for an extension of time under 37 C.F.R. 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this, concurrent and future replies, including extension of time fees, to Deposit Account 16-0607 and please credit any excess fees to such deposit account.

Respectfully submitted,  
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